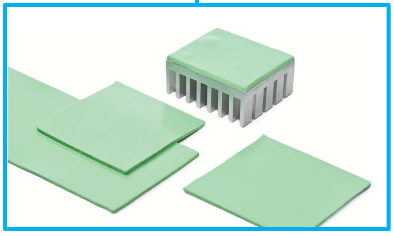
FT_TGF_066_AB_63

Thermal Pad



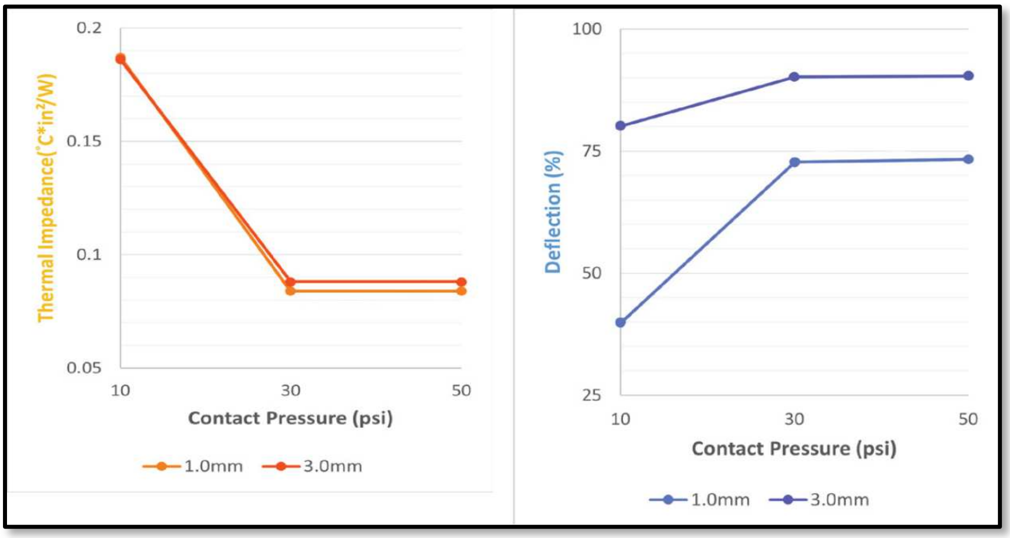
Our thermal foams also called Gap Pad or Gap Filler are silicone-based thermally conductive materials that solve heat dissipation problems. The TGF-066-AB is a specially designed mattress for applications requiring medium cooling. Indeed, it is an excellent thermal conductor of 6.5W/mK, with good thermal resistance thus facilitating heat transfer and also has excellent electrical insulation. Below 1mm, the mattress is difficult to use as a pick-in-place for robotic production, in this case it will be necessary to adjust its hardness before use. We can cut according to the client's plan.

Application areas: Electronic components - Electric vehicles, 5G, Automatic driving system, Mobile phone, AIOT, HPC (High Performance Computing), Server, IC, CPU, MOS, Motherboard, Power supply, Heat sink, LCD-TV, laptop, PC, telecom device, wireless hub, DDR ll module, etc.

Technical characteristics

Features	TGF-066-AB	Unit	Tolerance	Test Method
Color	Green	-	-	Colorimètre CIE 1976
Density	3.3	g/cm^3	+/- 10%	ASTM D792
Thickness	1 - 10	mm	-	ASTM D374
Hardness	25	shore 00	+/- 10	ASTM D2240
Sizes	310*310	mm	-	-
Thermal conductivity	6.5	W/mK	+/- 10%	ASTM D5470 Modified
Weight loss	< 1	%	-	ASTM E595 Modified
Elongation	60	%	-	ASTM D412
Breakdown voltage	≥ 4	kV/mm	-	ASTM D149
Volume resistance	10^{12}	Ohm-m	-	ASTM D257
UL certification	V-0	-	-	UL 94
Working Temperature	-50 to 150	°C	-	-

The TGF_066_AB is available in thicknesses from 1 to 10mm.



Results obtained under laboratory conditions and should be considered as a guide only. AB2E has no control over its customers' hardware and many other factors, it is the user's responsibility to perform their own tests to ensure that the product meets their needs.

REACH

ROHS